

Here are the fabrication instructions:

1. Board outline is 27 inch X 7.1 inch
2. Minimum trace width is 8 mils and minimum spacing is 8 mils
3. Board is made of FR-4: TG150, 2 oz copper, 6 layers. Total thickness is 1.6 mm
4. Board Assembly (stack up):

2E1-F_Cu.gbr	2 oz copper
2E1-In1_Cu.gbr	2 oz copper
2E1-In2_Cu.gbr	2 oz copper
2E1-In3_Cu.gbr	2 oz copper
2E1-In4_Cu.gbr	2 oz copper
2E1-B_Cu.gbr	2 oz copper
5. There are two solder mask layers, top (2E1-F_Mask.gbr) and bottom (2E1-B_Mask.gbr)
6. There are two silkscreen layers, top (2E1-F_Silkscreen.gbr) and bottom (2E1-B_Silkscreen.gbr)
7. There are two drill files for plated through holes (2E1-NPTH.drl and 2E1-PTH.drl)
8. There is one BOM files (BOM.xlsx)

Thank you